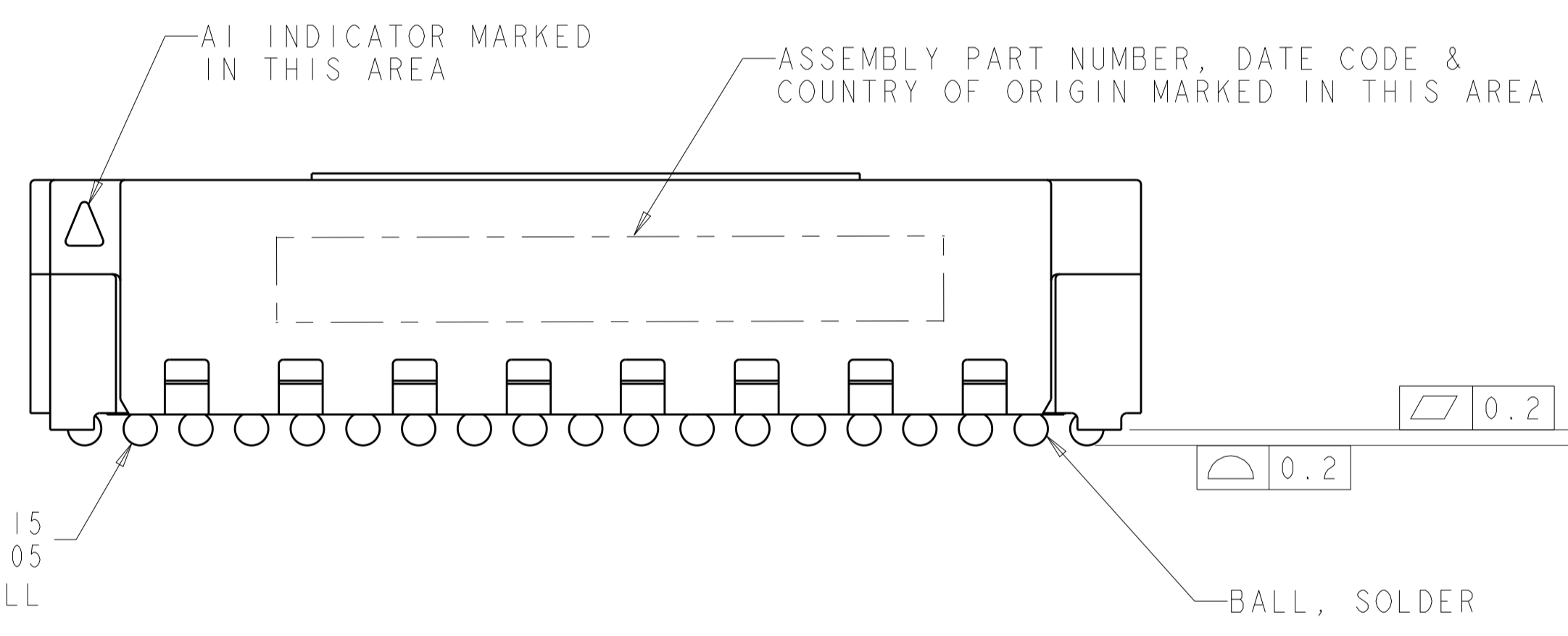
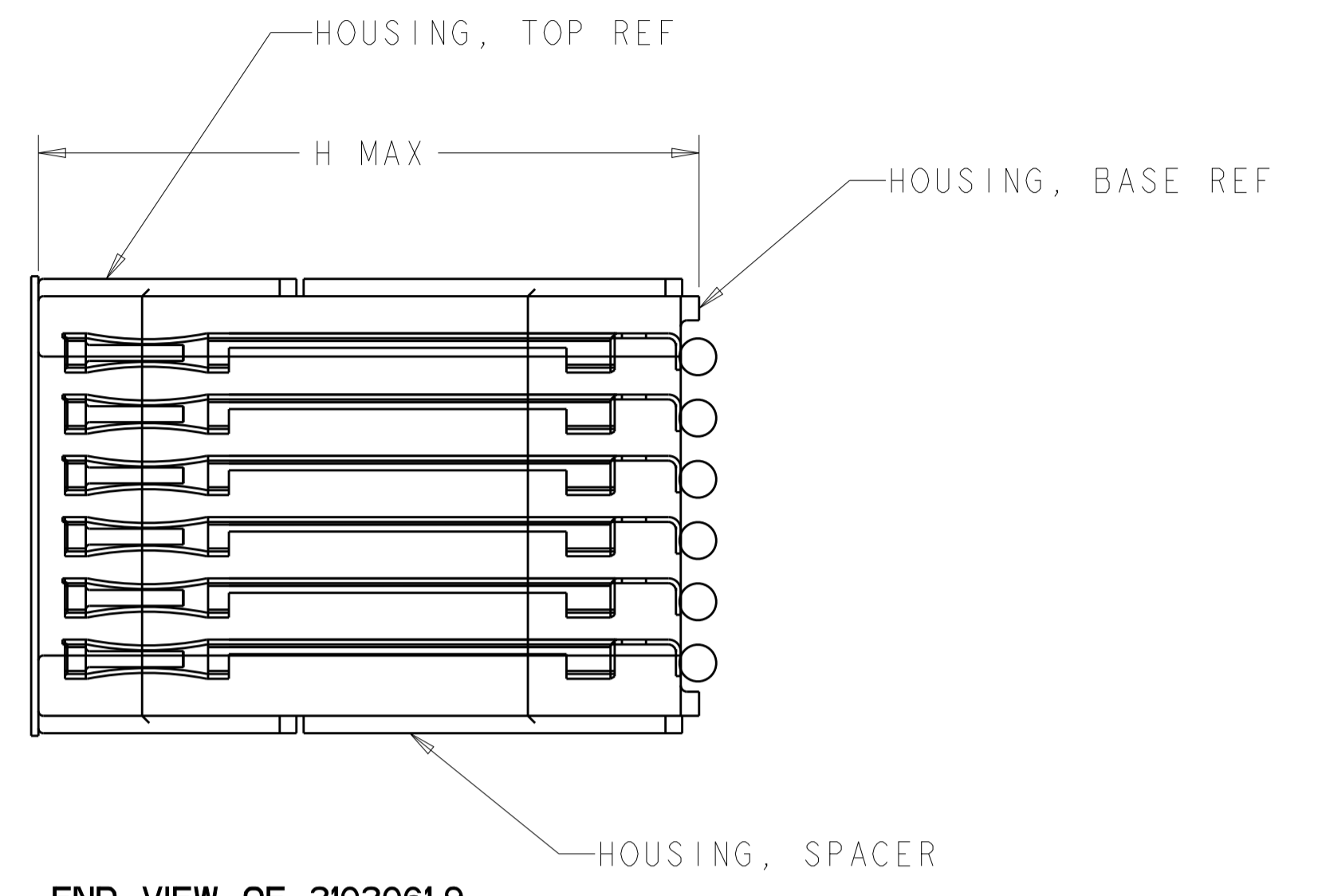
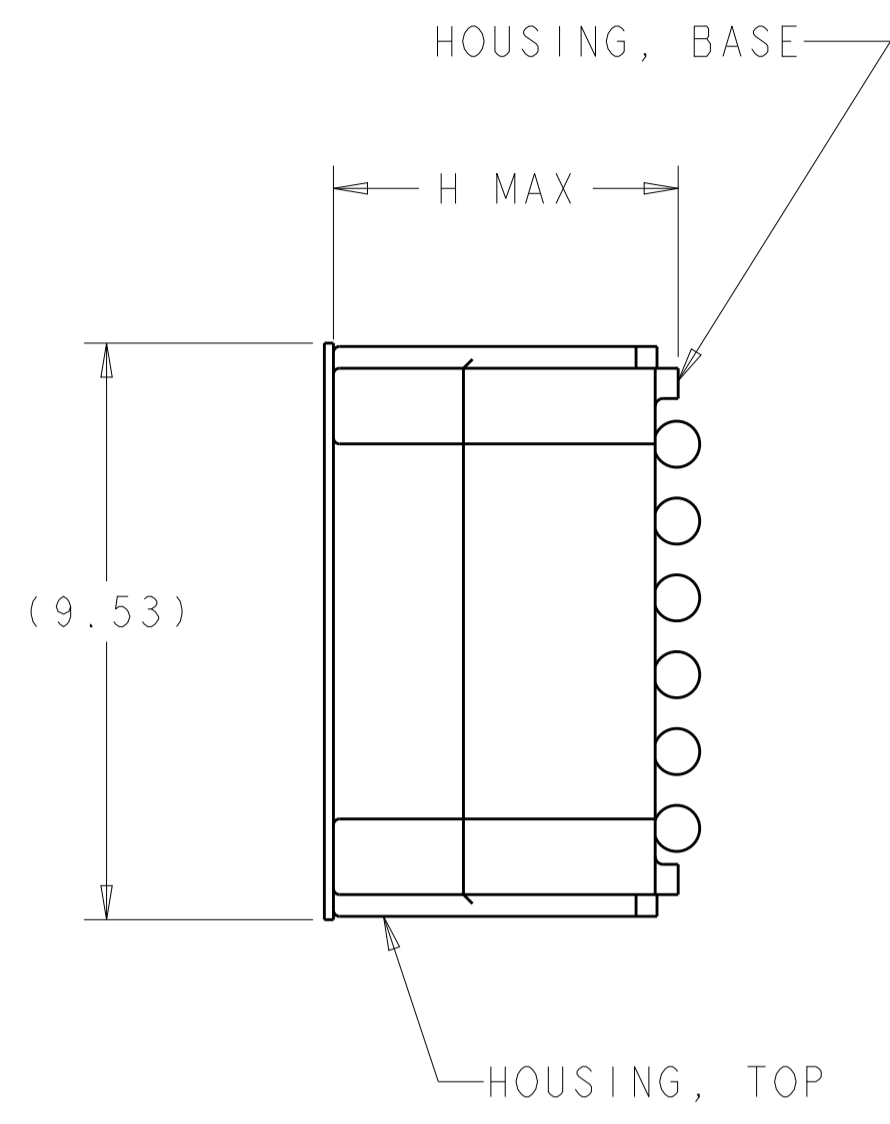
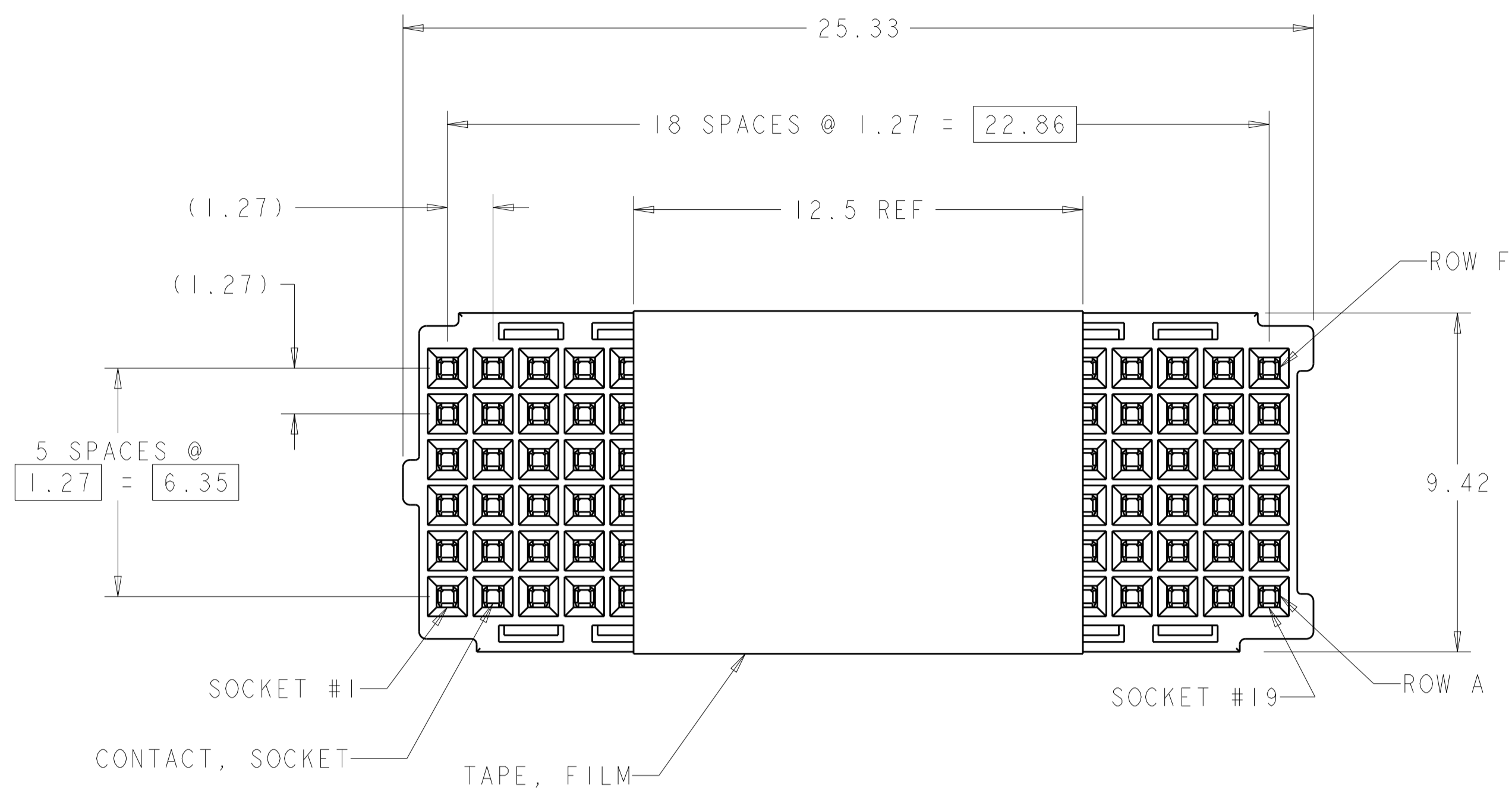
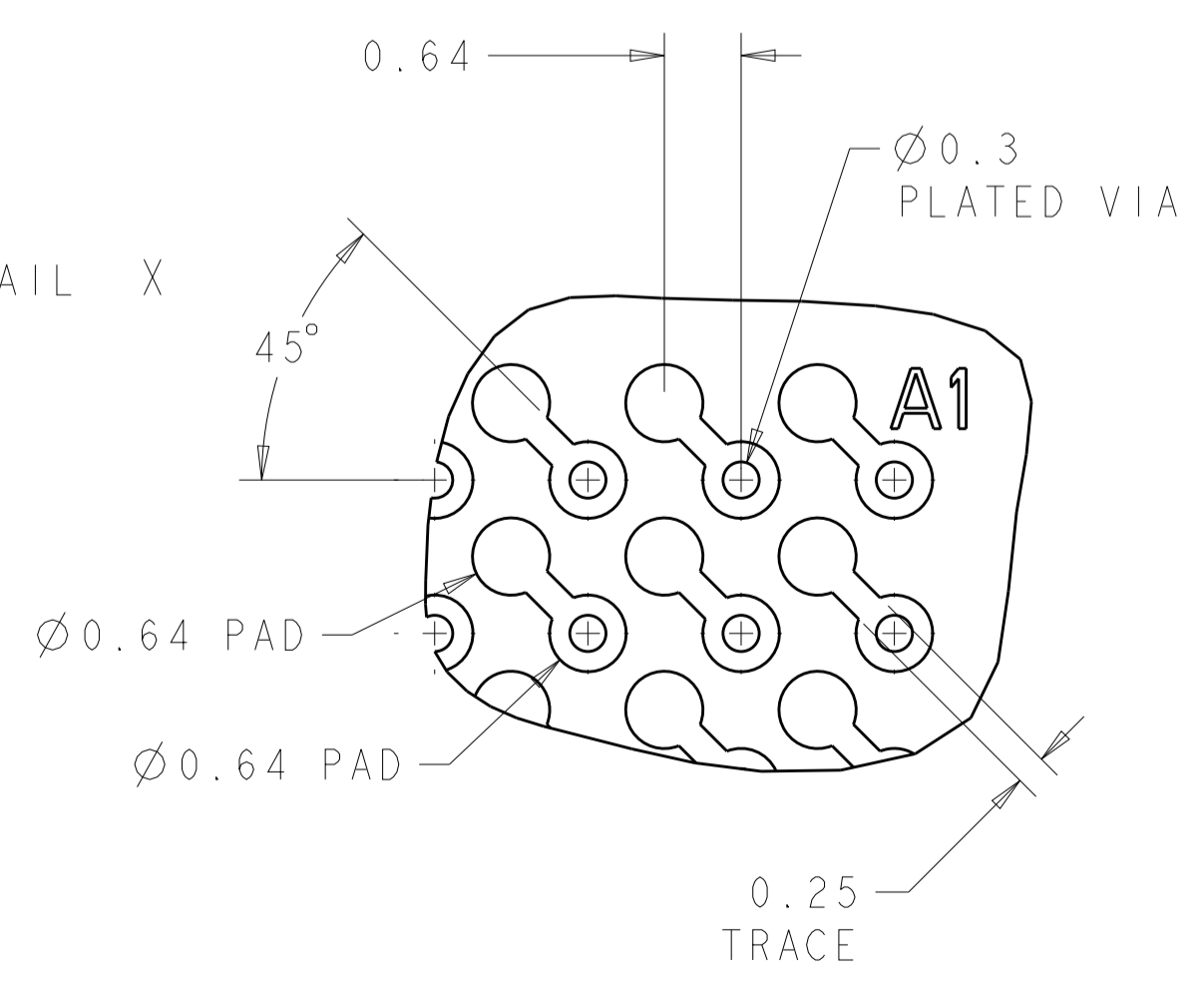
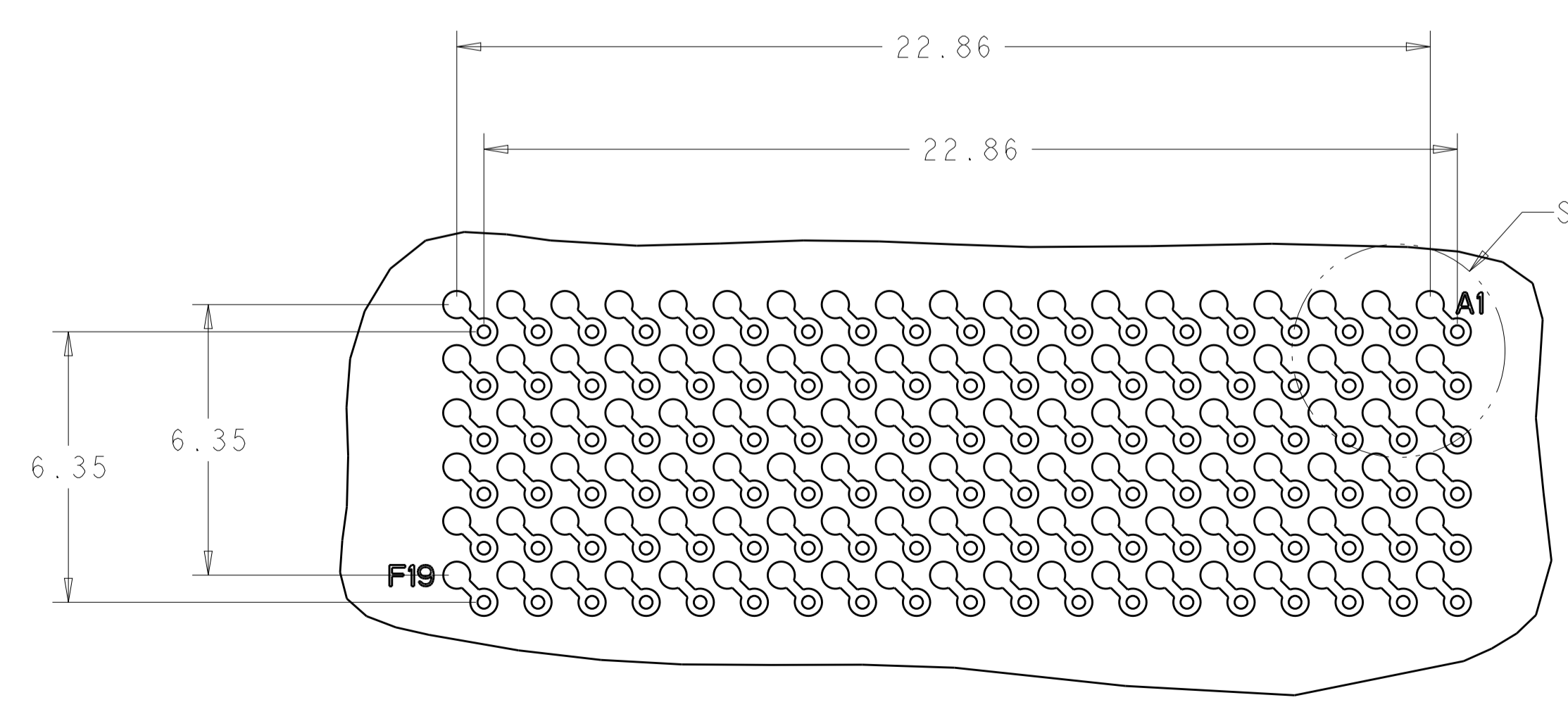
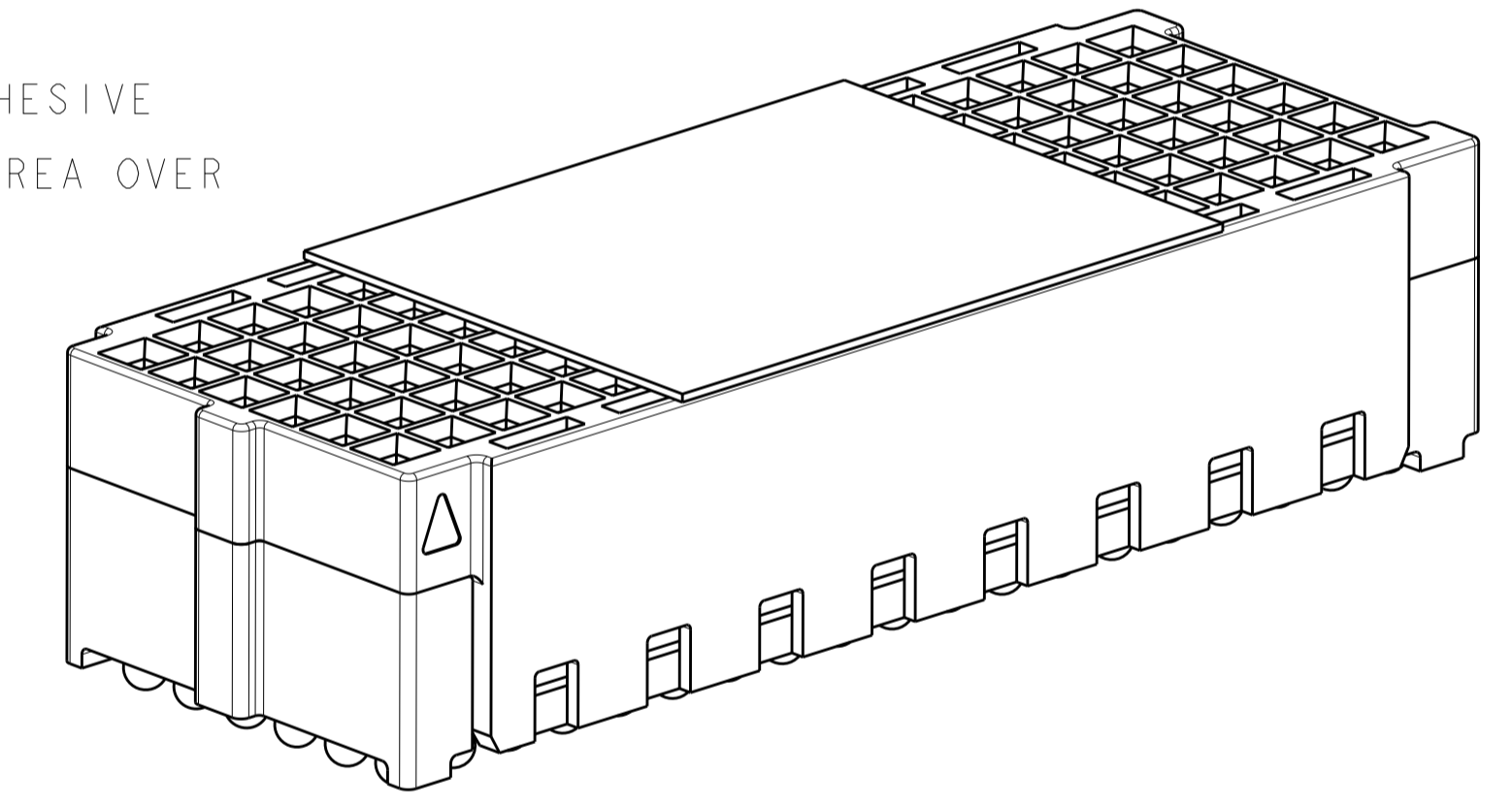


LOC		DIST		REVISIONS			
P	LTN	DESCRIPTION	DATE	DMN	APVD		
E		REV PER ECO 12-013333	7-26-12	CT	DH		



- △ MATERIAL: HOUSINGS; LCP, COLOR-NATURAL CONTACT; BERYLLIUM COPPER SOLDER BALL; SEE TABLE TAPE, FILM; KAPTON WITH SILICON ADHESIVE
- △ FINISH: CONTACT; GOLD (SEE TABLE) ON MATING AREA OVER NICKEL ON ENTIRE CONTACT.
- 3. PRODUCT IS PACKAGED ON TAPE AND REELED.
- △ PRELIMINARY- NOT RELEASED FOR PRODUCTION



△	2102060-4	15	0.76 μ m	11	LEAD FREE PER SAC405	1-2102061-6
△	2102060-3	15	0.76 μ m	11	TIN LEAD	1-2102061-5
△	2102060-2	15	1.27 μ m	11	LEAD FREE PER SAC405	1-2102061-4
△	2102060-1	15	1.27 μ m	11	TIN LEAD	1-2102061-3
	2102060-4	8	0.76 μ m	14	LEAD FREE PER SAC405	1-2102061-2
	2102060-3	8	0.76 μ m	14	TIN LEAD	1-2102061-1
	2102060-2	18	1.27 μ m	14	LEAD FREE PER SAC405	1-2102061-0
	2102060-1	18	1.27 μ m	14	TIN LEAD	2102061-9
	2102060-4	12	0.76 μ m	8	LEAD FREE PER SAC405	2102061-8
	2102060-3	12	0.76 μ m	8	TIN LEAD	2102061-7
	2102060-4	10	0.76 μ m	6	LEAD FREE PER SAC405	2102061-6
	2102060-3	10	0.76 μ m	6	TIN LEAD	2102061-5
	2102060-2	12	1.27 μ m	8	LEAD FREE PER SAC405	2102061-4
	2102060-1	12	1.27 μ m	8	TIN LEAD	2102061-3
	2102060-2	10	1.27 μ m	6	LEAD FREE PER SAC405	2102061-2
	2102060-1	10	1.27 μ m	6	TIN LEAD	2102061-1
	MATING PART NUMBER	MATED STACK HEIGHT (mm)	GOLD PLATING THICKNESS	H MAX REF	SOLDER BALL MATERIAL	PART NUMBER

PCB LAYOUT (CONNECTOR SIDE) SCALE 8:1

DETAIL X SCALE 16:1

THIS DRAWING IS A CONTROLLED DOCUMENT. DWG: G. DOWDY 23JUL2009. CHK: K. DOWHOWER 23JUL2009. APVD: K. DOWHOWER 23JUL2009.

DIMENSIONS: mm. TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±, 1 PLC ±, 2 PLC ±, 3 PLC ±, 4 PLC ±, ANGLES ±.

MATERIAL: △. FINISH: △.

STE TE Connectivity. NAME: ASSEMBLY, SOCKET, 114 POSITION, MINI-BOX STACKING CONNECTOR. SIZE: 108-2411. APPLICATION SPEC: 114-13279. WEIGHT: 114-13279. CUSTOMER DRAWING.

SCALE: 8:1. SHEET 1 OF 1. REV E.